



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



High-Loss, Thin, Elastomeric Microwave Absorber



HIGH-LOSS ELASTOMERIC ABSORBER

Eccosorb BSR is a thin, flexible, high-loss, electrically non-conductive silicone absorber. It is designed for the frequency range from 6 GHz to mm wave. It has low outgassing properties and high temperature resistance.

FEATURES AND BENEFITS

- High thermal stability
- Electrically non-conductive
- High magnetic loss

MARKETS

- Commercial Telecom
- Security and Defense
- Automotive and Industrial Electronics

SPECIFICATIONS

TYPICAL PROPERTIES	ECCOSORB BSR
Frequency Range (GHz)	≥ 6 GHz
Max Service Temperature °C (°F)	170 (338)
Fire Retardancy	UL94 V-0
Hardness (Shore A)	> 70
Elongation (%)	50
Tensile Strength (MPa)	5.0
Volume Resistivity (ohm-cm)	2×10^8
Thermal Expansion per °C (°F)	63×10^{-6} (35×10^{-6})
Dielectric Strength (volts/mil)	>10
Outgassing (%TML) (%CVCN)*	0.47/0.28

*Data for design engineer guidance only. Observed performance varies in application.
Engineers are reminded to test the material in application.*

* Outgassing data per ASTM E595-07; criteria for acceptability is 1.00% TML and 0.10% CVCN.

APPLICATIONS

- Eccosorb BSR is engineered to reduce or eliminate surface currents, cavity resonance, coupling, and generally dampen reflections. It will significantly improve the operation of microwave devices by lowering the Q of cavities.
- Eccosorb BSR is recommended for use in high reliability aerospace, military, and space applications, exhibiting excellent thermal cycling, shock and vibration absorption characteristics.
- Some other applications include power amplifiers, oscillators and down/up converters.

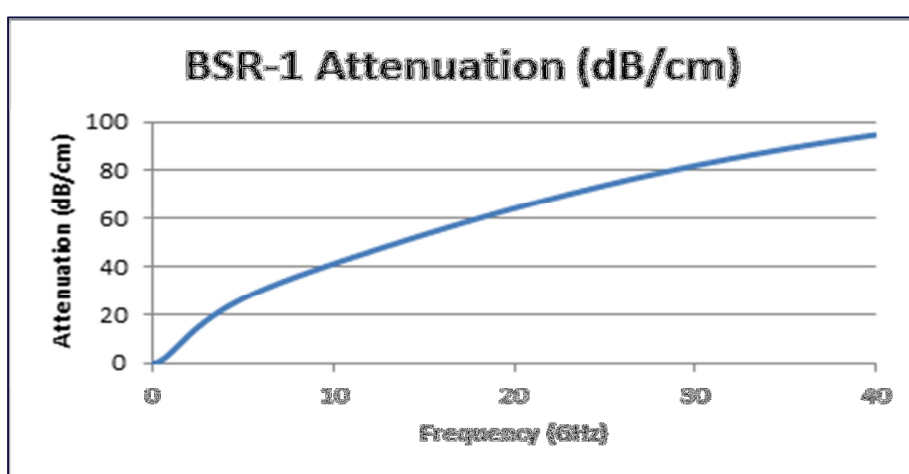
AVAILABILITY

- Standard sheets are 305 x 305mm (12"x12").
- Standard thicknesses are 0.25mm (0.010"), 0.50mm (0.020"), 1.0mm (0.040"), 1.5mm (0.060") and 2.54mm (0.100").
- For most applications Eccosorb BSR can be supplied with a Pressure Sensitive Adhesive.
- Eccosorb BSR is available in other sizes, thicknesses and customer specified configurations upon request. This includes die cut and kiss cut parts to reduce installation labor by allowing quick assembly.

INSTRUCTIONS FOR USE

- Eccosorb BSR is designed to function directly in front of a metallic surface.
- For applications where the service temperature exceeds 121°C (250°F), the material can be bonded to most substrates by using an RTV silicone based adhesive in conjunction with a suitable primer.
- Eccosorb BSR can be readily cut with a sharp knife and template. It is a very flexible material and conforms to contoured surfaces.

Typical Attenuation Eccosorb BSR



RFP-DS-BSR 093015

Any information furnished by Laird Technologies, Inc. and its agents is believed to be accurate and reliable. All specifications are subject to change without notice. Responsibility for the use and application of Laird Technologies materials rests with the end user. Laird Technologies makes no warranties as to the fitness, merchantability, suitability or non-infringement of any Laird Technologies materials or products for any specific or general uses. Laird Technologies shall not be liable for incidental or consequential damages of any kind. All Laird Technologies products are sold pursuant to the Laird Technologies' Terms and Conditions of sale in effect from time to time, a copy of which will be furnished upon request. © Copyright 2015 Laird Technologies, Inc. All Rights Reserved. Laird, Laird Technologies, the Laird Technologies Logo, and other marks are trademarks or registered trademarks of Laird Technologies, Inc. or an affiliate company thereof. Other product or service names may be the property of third parties. Nothing herein provides a license under any Laird Technologies or any third party intellectual property rights.